

Notice of References Cited		Application/Control No.	Applicant(s)/Patent Under Reexamination LEE ET AL.	
		Examiner Caridad M. Everhart	Art Unit 2891	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-5,354,712	10-1994	Ho et al.	438/643
	B	US-6,255,192	07-2001	Dornisch, Dieter	438/430
	C	US-6,696,338	02-2004	Oh et al.	438/253
	D	US-5,970,374	10-1999	Teo, Yeow Meng	438/629
	E	US-6,645,851	11-2003	Ho et al.	438/626
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Nishimura, et al ""Reliable Submicron Vias Using Aluminum Alloy High Temperature Sputter Filling". 1991 Proc. 8 th International IEEE VLSI Multilevel Interconnection Conf. June 11-12, 1991, Santa Clara, CA pp. 170-176.
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.